# Low-Voltage CMOS Hex Inverter

## With 5 V-Tolerant Inputs

The MC74LCX04 is a high performance hex inverter operating from a 2.0 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_{\rm I}$  specification of 5.5 V allows MC74LCX04 inputs to be safely driven from 5 V devices if  $V_{\rm CC}$  is less than 5.0 V.

Current drive capability is 24 mA at the outputs.

#### **Features**

- Designed for 2.0 V to 5.5 V V<sub>CC</sub> Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

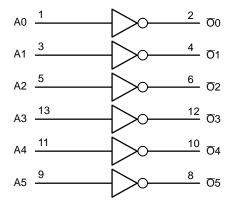


Figure 1. Logic Diagram



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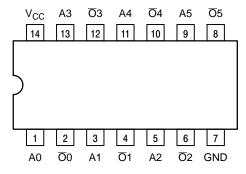
http://onsemi.com





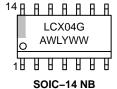
SOIC-14 NB D SUFFIX CASE 751A TSSOP-14 DT SUFFIX CASE 948G

#### **PIN ASSIGNMENT**



14-Lead (Top View)

#### **MARKING DIAGRAMS**





TSSOP-14

A = Assembly Location

WL, L = Wafer Lot YY. Y = Year

WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### **PIN NAMES**

| Pins                 | Function            |
|----------------------|---------------------|
| An<br><del>O</del> n | Data Inputs Outputs |

#### **TRUTH TABLE**

| An | Ōn |
|----|----|
| L  | H  |
| H  | L  |

#### **MAXIMUM RATINGS**

| Symbol           | Parameter                        | Value                             | Condition                            | Unit |
|------------------|----------------------------------|-----------------------------------|--------------------------------------|------|
| V <sub>CC</sub>  | DC Supply Voltage                | -0.5 to +7.0                      |                                      | V    |
| VI               | DC Input Voltage                 | $-0.5 \le V_1 \le +7.0$           |                                      | V    |
| Vo               | DC Output Voltage                | $-0.5 \le V_{O} \le V_{CC} + 0.5$ | Output in HIGH or LOW State (Note 1) | V    |
| I <sub>IK</sub>  | DC Input Diode Current           | -50                               | V <sub>I</sub> < GND                 | mA   |
| I <sub>OK</sub>  | DC Output Diode Current          | -50                               | V <sub>O</sub> < GND                 | mA   |
|                  |                                  | +50                               | V <sub>O</sub> > V <sub>CC</sub>     | mA   |
| I <sub>O</sub>   | DC Output Source/Sink Current    | ±50                               |                                      | mA   |
| I <sub>CC</sub>  | DC Supply Current Per Supply Pin | ±100                              |                                      | mA   |
| I <sub>GND</sub> | DC Ground Current Per Ground Pin | ±100                              |                                      | mA   |
| T <sub>STG</sub> | Storage Temperature Range        | -65 to +150                       |                                      | °C   |
| MSL              | Moisture Sensitivity             |                                   | Level 1                              |      |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

| Symbol          | Pa                                 | Parameter  |            | Тур                  | Max              | Unit |
|-----------------|------------------------------------|--|------------|----------------------|------------------|------|
| V <sub>CC</sub> | Supply Voltage                     | Operating<br>Data Retention Only   | 2.0<br>1.5 | 2.5, 3.3<br>2.5, 3.3 | 5.5<br>5.5       | V    |
| VI              | Input Voltage                      |  | 0          |                      | 5.5              | V    |
| Vo              | Output Voltage                     | (HIGH or LOW State) (3–State)  | 0          |                      | V <sub>CC</sub>  | V    |
| Іон             | HIGH Level Output Current          | $V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$<br>$V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$<br>$V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$ |            |                      | -24<br>-12<br>-8 | mA   |
| I <sub>OL</sub> | LOW Level Output Current           | V <sub>CC</sub> = 3.0 V - 3.6 V<br>V <sub>CC</sub> = 2.7 V - 3.0 V<br>V <sub>CC</sub> = 2.3 V - 2.7 V                            |            |                      | +24<br>+12<br>+8 | mA   |
| T <sub>A</sub>  | Operating Free-Air Temperature     |  | -55        |                      | +125             | °C   |
| Δt/ΔV           | Input Transition Rise or Fall Rate | , $V_{IN}$ from 0.8 V to 2.0 V, $V_{CC}$ = 3.0 V   | 0          |                      | 10               | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

<sup>1.</sup> I<sub>O</sub> absolute maximum rating must be observed.

#### DC ELECTRICAL CHARACTERISTICS

|                  |                                       |   | $T_A = -55^{\circ}C \text{ to } +125^{\circ}C$ |      |      |
|------------------|---------------------------------------|---|--|------|------|
| Symbol           | Characteristic                        | Condition   | Min  | Max  | Unit |
| V <sub>IH</sub>  | HIGH Level Input Voltage (Note 2)     | 2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V   | 1.7  |      | V    |
|                  |                                       | 2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V   | 2.0  |      |      |
| V <sub>IL</sub>  | LOW Level Input Voltage (Note 2)      | 2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V   |  | 0.7  | V    |
|                  |                                       | 2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V   |  | 0.8  |      |
| V <sub>OH</sub>  | HIGH Level Output Voltage             | $2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = -100 \mu\text{A}$ | V <sub>CC</sub> - 0.2                          |      | V    |
|                  |                                       | $V_{CC} = 2.3 \text{ V; } I_{OH} = -8 \text{ mA}$                                     | 1.8  |      |      |
|                  |                                       | V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA                                     | 2.2  |      |      |
|                  |                                       | $V_{CC} = 3.0 \text{ V; } I_{OH} = -18 \text{ mA}$                                    | 2.4  |      |      |
|                  |                                       | $V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$                                     | 2.2  |      |      |
| V <sub>OL</sub>  | LOW Level Output Voltage              | $2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$  |  | 0.2  | V    |
|                  |                                       | V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 8 mA                                       |  | 0.6  |      |
|                  |                                       | V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA                                      |  | 0.4  |      |
|                  |                                       | V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA                                      |  | 0.4  |      |
|                  |                                       | V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA                                      |  | 0.55 |      |
| I <sub>OFF</sub> | Power Off Leakage Current             | V <sub>CC</sub> = 0, V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V              |  | 10   | μΑ   |
| I <sub>IN</sub>  | Input Leakage Current                 | V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND                               |  | ±5   | μΑ   |
| I <sub>CC</sub>  | Quiescent Supply Current              | V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND                               |  | 10   | μΑ   |
| $\Delta I_{CC}$  | Increase in I <sub>CC</sub> per Input | $2.3 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$                   |  | 500  | μΑ   |

<sup>2.</sup> These values of  $V_I$  are used to test DC electrical characteristics only.

#### AC CHARACTERISTICS ( $t_R = t_F = 2.5 \text{ ns}; R_L = 500 \Omega$ )

|                  |                        |          |                       | Limits                           |                    |       |                       |               |      |
|------------------|------------------------|----------|-----------------------|----------------------------------|--------------------|-------|-----------------------|---------------|------|
|                  |                        |          |                       | T <sub>A</sub> = -55°C to +125°C |                    |       |                       |               |      |
|                  |                        |          | V <sub>CC</sub> = 3.3 | V ± 0.3 V                        | V <sub>CC</sub> =  | 2.7 V | V <sub>CC</sub> = 2.5 | $V \pm 0.2 V$ |      |
|                  |                        |          | C <sub>L</sub> = 9    | 50 pF                            | C <sub>L</sub> = 5 | 50 pF | C <sub>L</sub> = 3    | 30 pF         |      |
| Symbol           | Parameter              | Waveform | Min                   | Max                              | Min                | Max   | Min                   | Max           | Unit |
| t <sub>PLH</sub> | Propagation Delay Time | 1        | 1.5                   | 5.2                              | 1.5                | 6.0   | 1.5                   | 6.2           | ns   |
| t <sub>PHL</sub> | Input to Output        |          | 1.5                   | 5.2                              | 1.5                | 6.0   | 1.5                   | 6.2           |      |
| toshl            | Output-to-Output Skew  |          |                       | 1.0                              |                    |       |                       |               | ns   |
| toslh            | (Note 3)               |          |                       | 1.0                              |                    |       |                       |               |      |

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

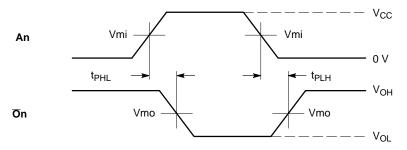
# DYNAMIC SWITCHING CHARACTERISTICS

|                  |                            |   | T <sub>A</sub> = +25°C |      |     |      |
|------------------|----------------------------|---|------------------------|------|-----|------|
| Symbol           | Characteristic             | Condition   | Min                    | Тур  | Max | Unit |
| V <sub>OLP</sub> | Dynamic LOW Peak Voltage   | $V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ |                        | 0.8  |     | V    |
|                  | (Note 4)                   | $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$ |                        | 0.6  |     | V    |
| V <sub>OLV</sub> | Dynamic LOW Valley Voltage | $V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ |                        | -0.8 |     | V    |
|                  | (Note 4)                   | $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$ |                        | -0.6 |     | V    |

<sup>4.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

#### **CAPACITIVE CHARACTERISTICS**

| Symbol           | Parameter                     | Condition  | Typical | Unit |
|------------------|-------------------------------|--|---------|------|
| C <sub>IN</sub>  | Input Capacitance             | $V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$ | 7       | pF   |
| C <sub>OUT</sub> | Output Capacitance            | $V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$ | 8       | pF   |
| C <sub>PD</sub>  | Power Dissipation Capacitance | 10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$    | 25      | pF   |

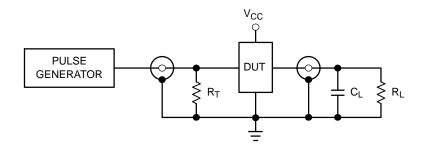


#### **WAVEFORM 1 – PROPAGATION DELAYS**

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

|        | V <sub>CC</sub> |       |                    |  |  |
|--------|-----------------|-------|--------------------|--|--|
| Symbol | 3.3 V ± 0.3 V   | 2.7 V | 2.5 V ± 0.2 V      |  |  |
| Vmi    | 1.5 V           | 1.5 V | V <sub>CC</sub> /2 |  |  |
| Vmo    | 1.5 V           | 1.5 V | V <sub>CC</sub> /2 |  |  |

Figure 2. AC Waveforms



 $C_L=50$  pF at  $V_{CC}=3.3\pm0.3$  V or equivalent (includes jig and probe capacitance)  $C_L=30$  pF at  $V_{CC}=2.5\pm0.2$  V or equivalent (includes jig and probe capacitance)  $R_L=R_1=500~\Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 3. Test Circuit

#### **ORDERING INFORMATION**

| Device           | Package                 | Shipping <sup>†</sup> |
|------------------|-------------------------|-----------------------|
| MC74LCX04DG      | SOIC-14 NB<br>(Pb-Free) | 55 Units / Rail       |
| MC74LCX04DR2G    | SOIC-14 NB<br>(Pb-Free) | 2500 Tape & Reel      |
| MC74LCX04DTG     | TSSOP-14<br>(Pb-Free)   | 96 Units / Rail       |
| MC74LCX04DTR2G   | TSSOP-14<br>(Pb-Free)   | 2500 Tape & Reel      |
| NLV74LCX04DTR2G* | TSSOP-14<br>(Pb-Free)   | 2500 Tape & Reel      |

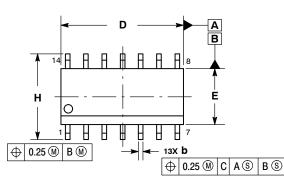
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable

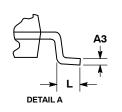


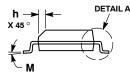
△ 0.10

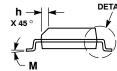
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**DATE 03 FEB 2016** 





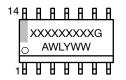




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ASME Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
- MAXIMUM MATERIAL CONDITION.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

|     | MILLIN | IETERS | INC   | HES   |
|-----|--------|--------|-------|-------|
| DIM | MIN    | MAX    | MIN   | MAX   |
| Α   | 1.35   | 1.75   | 0.054 | 0.068 |
| A1  | 0.10   | 0.25   | 0.004 | 0.010 |
| АЗ  | 0.19   | 0.25   | 0.008 | 0.010 |
| b   | 0.35   | 0.49   | 0.014 | 0.019 |
| D   | 8.55   | 8.75   | 0.337 | 0.344 |
| Е   | 3.80   | 4.00   | 0.150 | 0.157 |
| e   | 1.27   | BSC    | 0.050 | BSC   |
| H   | 5.80   | 6.20   | 0.228 | 0.244 |
| h   | 0.25   | 0.50   | 0.010 | 0.019 |
| L   | 0.40   | 1.25   | 0.016 | 0.049 |
| М   | 0 °    | 7°     | 0 °   | 7°    |

#### **GENERIC MARKING DIAGRAM\***

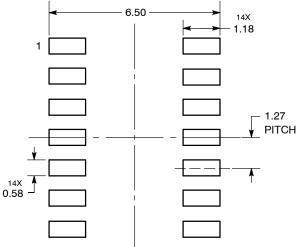


XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator. "G" or microdot " ■". may or may not be present.

# **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

C SEATING PLANE

#### **STYLES ON PAGE 2**

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

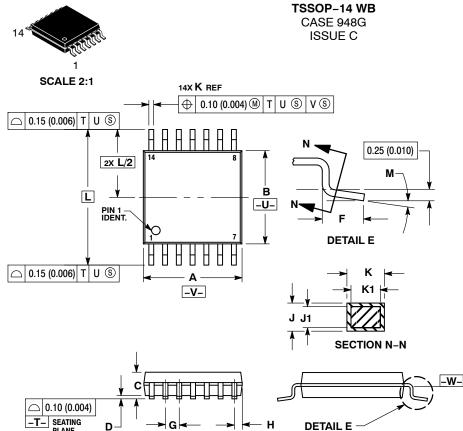
#### SOIC-14 CASE 751A-03 ISSUE L

#### DATE 03 FEB 2016

| STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE | STYLE 2:<br>CANCELLED   | STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE  | STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE  |
|---|---|---|---|
| STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE | STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE | STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE | STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE |

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| DESCRIPTION:     | SOIC-14 NB  |   | PAGE 2 OF 2 |

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**SOLDERING FOOTPRINT** 

7.06

14X

1.26

**DATE 17 FEB 2016** 

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

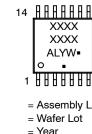
  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

|     | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
| DIM | MIN         | MAX  | MIN       | MAX   |
| Α   | 4.90        | 5.10 | 0.193     | 0.200 |
| В   | 4.30        | 4.50 | 0.169     | 0.177 |
| С   |             | 1.20 |           | 0.047 |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |
| G   | 0.65 BSC    |      | 0.026 BSC |       |
| Н   | 0.50        | 0.60 | 0.020     | 0.024 |
| J   | 0.09        | 0.20 | 0.004     | 0.008 |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |
| L   | 6.40 BSC    |      | 0.252 BSC |       |
| М   | o o         | ρ °  | 0 °       | Q°    |

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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**DIMENSIONS: MILLIMETERS** 

0.65

**PITCH** 

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